



ANALOG DEVICES

Dual 12-Bit, High Bandwidth, Multiplying DAC with 4-Quadrant Resistors and Parallel Interface

AD5405

FEATURES

On chip 4-quadrant resistors allow flexible output ranges
10 MHz multiplying bandwidth
Fast parallel interface write cycle: 58 MSPS
2.5 V to 5.5 V supply operation
 ± 10 V reference input
Extended temperature range: -40°C to 125°C
40-lead LFCSP package
Guaranteed monotonic
4-quadrant multiplication
Power-on reset
Readback function
.5 μA typical current consumption

APPLICATIONS

Portable battery-powered applications
Waveform generators
Analog processing
Instrumentation applications
Programmable amplifiers and attenuators
Digitally-controlled calibration
Programmable filters and oscillators
Composite video
Ultrasound
Gain, offset, and voltage trimming

GENERAL DESCRIPTION

The AD5405¹ is a dual CMOS, 12-bit, current output digital-to-analog converter (DAC). This device operates from a 2.5 V to 5.5 V power supply, making it suited to battery-powered and other applications.

The applied external reference input voltage (V_{REF}) determines the full-scale output current. An integrated feedback resistor (R_{FB}) provides temperature tracking and full-scale voltage output when combined with an external I-to-V precision amplifier. This device also contains all the 4-quadrant resistors necessary for bipolar operation and other configuration modes.

This DAC utilizes data readback, allowing the user to read the contents of the DAC register via the DB pins. On power-up, the internal register and latches are filled with zeros and the DAC outputs are at zero scale.

As a result of manufacture with a CMOS submicron process, the device offers excellent 4-quadrant multiplication characteristics, with large signal multiplying bandwidths of up to 10 MHz.

The AD5405 has a 6 mm \times 6 mm, 40-lead LFCSP package.

¹ US Patent Number 5,689,257.

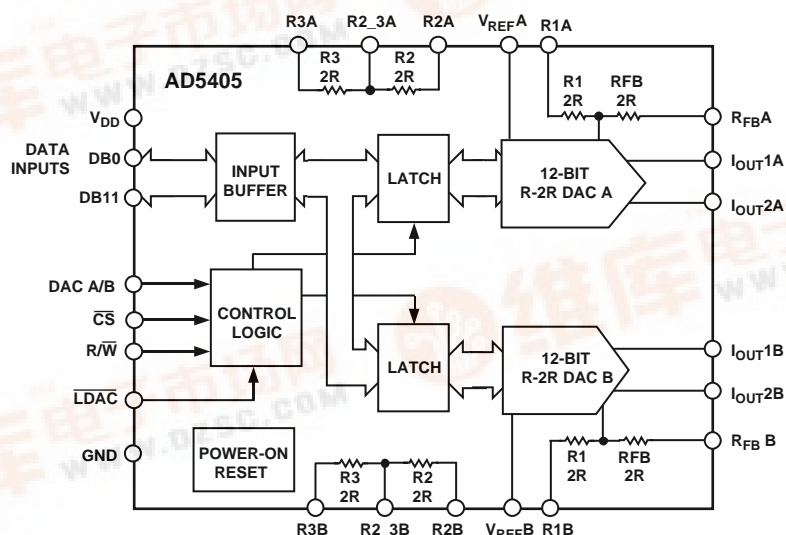


Figure 1. AD5405 Functional Block Diagram



TABLE OF CONTENTS

Specifications.....	3	Adding Gain.....	15
Timing Characteristics.....	5	Used as a Divider or Programmable Gain Element.....	16
Absolute Maximum Ratings.....	6	Reference Selection	16
ESD Caution.....	6	Amplifier Selection	16
Pin Configuration and Function Descriptions.....	7	Parallel Interface.....	17
Typical Performance Characteristics	8	Microprocessor Interfacing.....	17
Terminology	13	PCB Layout and Power Supply Decoupling	17
General Description	14	Evaluation Board for the DACs.....	18
DAC Section.....	14	Overview of AD54xx Devices.....	22
Circuit Operation	14	Outline Dimensions	23
Single-Supply Applications.....	15	Ordering Guide	23
Positive Output Voltage	15		

REVISION HISTORY

7/04—Revision 0: Initial Version

SPECIFICATIONS¹

$V_{DD} = 2.5\text{ V to }5.5\text{ V}$, $V_{REFA} = V_{REFB} = 10\text{ V}$, $I_{OUT2} = 0\text{ V}$. All specifications T_{MIN} to T_{MAX} , unless otherwise noted. DC performance measured with OP1177, AC performance with AD9631, unless otherwise noted.

Table 1.

Parameter	Min	Typ	Max	Unit	Conditions
STATIC PERFORMANCE					
Resolution			12	Bits	Guaranteed monotonic
Relative Accuracy			±1	LSB	
Differential Nonlinearity			−1/+2	LSB	
Gain Error			±25	mV	
Gain Error Temp Coefficient ²		±5		ppm FSR/°C	
Bipolar Zero-Code Error			±25	mV	Data = 0x0000, T _A = 25°C, I _{OUT1}
Output Leakage Current			±1	nA	Data = 0x0000 _H , I _{OUT1}
			±10	nA	
REFERENCE INPUT					
Reference Input Range		±10		V	Typical resistor TC = −50 ppm/°C
V _{REFA} , V _{REFB} Input Resistance	8	10	12	kΩ	DAC input resistance
V _{REFA} to V _{REFB} Input Resistance Mismatch		1.6	2.5	%	Typ = 25°C, Max = 125°C
R ₁ , R _{FB} Resistance	16	20	24	kΩ	Typ = 25°C, Max = 125°C
R ₂ , R ₃ Resistance	16	20	24	kΩ	
R ₂ to R ₃ Resistance Mismatch		.06	.18	%	
DIGITAL INPUTS/OUTPUT					
Input High Voltage, V _{IH}	1.7			V	V _{DD} = 2.5 V to 5.5 V
Input Low Voltage, V _{IL}			0.8	V	V _{DD} = 2.7 V to 5.5 V
			0.7	V	V _{DD} = 2.5 V to 2.7 V
Input Leakage Current, I _{IL}			1	μA	
Input Capacitance			10	pF	
V _{DD} = 4.5 V to 5.5 V					
Output Low Voltage, V _{OL}			0.4	V	I _{SINK} = 200 μA
Output High Voltage, V _{OH}	V _{DD} − 1			V	I _{SOURCE} = 200 μA
V _{DD} = 2.5 V to 3.6 V					
Output Low Voltage, V _{OL}			0.4	V	I _{SINK} = 200 μA
Output High Voltage, V _{OH}	V _{DD} −0.5			V	I _{SOURCE} = 200 μA
DYNAMIC PERFORMANCE					
Reference Multiplying BW		10		MHz	V _{REF} = 5 V pk-pk, DAC loaded all 1s
Output Voltage Settling Time		80	120	ns	Measured to ±1 mV of FS. R _{LOAD} = 100 Ω, C _{LOAD} =15 pF. DAC latch alternately loaded with 0s and 1s.
Digital Delay		20	40	ns	1 LSB change around major carry, V _{REF} = 0 V DAC latch loaded with all 0s. Reference = 10 kHz DAC latches loaded with all 0s DAC latches loaded with all 1s Feedthrough to DAC output with $\overline{\text{CS}}$ high and alternate loading of all 0s and all 1s
Digital-to-Analog Glitch Impulse		3		nV-s	
Multiplying Feedthrough Error			−75	dB	
Output Capacitance			2	pF	
			4	pF	
Digital Feedthrough		5		nV-s	Feedthrough to DAC output with $\overline{\text{CS}}$ high and alternate loading of all 0s and all 1s
Total Harmonic Distortion		−75		dB	V _{REF} = 5 V p-p, all 1s loaded, f = 1 kHz
		−75		dB	V _{REF} = 5 V, sine wave generated from digital code
Output Noise Spectral Density		25		nV/√Hz	@ 1 kHz

AD5405

Parameter	Min	Typ	Max	Unit	Conditions
SFDR Performance (Wideband)					
Clock = 10 MHz					
500 kHz f_{OUT}		55		dB	
100 kHz f_{OUT}		63		dB	
50 kHz f_{OUT}		65		dB	
Clock = 25 MHz					
500 kHz f_{OUT}		50		dB	
100 kHz f_{OUT}		60		dB	
50 kHz f_{OUT}		62		dB	
SFDR Performance (Narrow Band)					
Clock = 10 MHz					
500 kHz f_{OUT}		73		dB	
100 kHz f_{OUT}		80		dB	
50k Hz f_{OUT}		87		dB	
Clock = 25 MHz					
500 kHz f_{OUT}		70		dB	
100 kHz f_{OUT}		75		dB	
50k Hz f_{OUT}		80		dB	
Intermodulation Distortion					
Clock = 10 MHz					
$f_1 = 400$ kHz, $f_2 = 500$ kHz		65		dB	
$f_1 = 40$ kHz, $f_2 = 50$ kHz		72		dB	
Clock = 25 MHz					
$f_1 = 400$ kHz, $f_2 = 500$ kHz		51		dB	
$f_1 = 40$ kHz, $f_2 = 50$ kHz		65		dB	
POWER REQUIREMENTS					
Power Supply Range	2.5		5.5	V	
I_{DD}			10	μ A	Logic inputs = 0 V or V_{DD}
Power Supply Sensitivity			0.001	%/%	$\Delta V_{DD} = \pm 5\%$

¹ Temperature range for Y version is -40°C to $+125^{\circ}\text{C}$.

² Guaranteed by design, not subject to production test.

TIMING CHARACTERISTICS

$V_{DD} = 2.5\text{ V to }5.5\text{ V}$, $V_{REF} = 5\text{ V}$, $I_{OUT2} = 0\text{ V}$. All specifications T_{MIN} to T_{MAX} , unless otherwise noted.

Table 2.

Parameter ^{1,2}	Limit at T_{MIN} , T_{MAX}	Unit	Conditions/Comments
Write Mode			
t_1	0	ns min	R/\overline{W} to \overline{CS} setup time
t_2	0	ns min	R/\overline{W} to \overline{CS} hold time
t_3	10	ns min	\overline{CS} low time
t_4	10	ns min	Address setup time
t_5	0	ns min	Address hold time
t_6	6	ns min	Data setup time
t_7	0	ns min	Data hold time
t_8	5	ns min	R/\overline{W} high to \overline{CS} low
t_9	7	ns min	\overline{CS} min high time
Data Readback Mode			
t_{10}	0	ns typ	Address setup time
t_{11}	0	ns typ	Address hold time
t_{12}	5	ns typ	Data access time
	35	ns max	
t_{13}	5	ns typ	Bus relinquish time
	10	ns max	

¹ See Figure 2. Temperature range for Y version is -40°C to $+125^\circ\text{C}$. Guaranteed by design and characterization, not subject to production test.

² All input signals are specified with $t_r = t_f = 5\text{ ns}$ (10% to 90% of V_{DD}) and timed from a voltage level of $(V_{IL} + V_{IH})/2$. Digital output timing measured with load circuit in Figure 3.

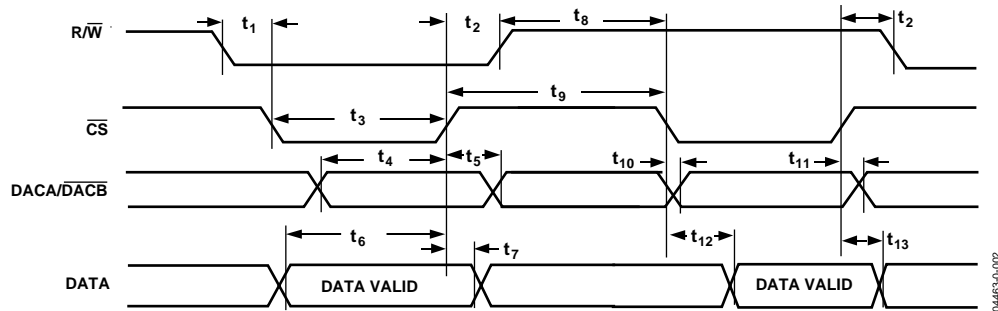


Figure 2. Timing Diagram

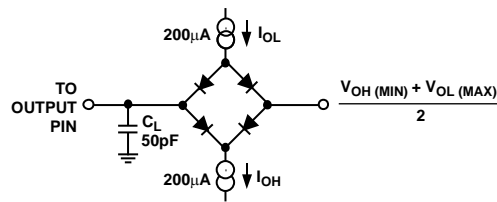


Figure 3. Load Circuit for Data Timing Specifications

AD5405

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 3.

Parameter	Rating
V_{DD} to GND	−0.3 V to +7 V
V_{REFA} , V_{REFB} , R_{FA} , R_{FB} to GND	−12 V to +12 V
I_{OUT1} , I_{OUT2} to GND	−0.3 V to +7 V
Logic Inputs and Output ¹	−0.3V to $V_{DD} + 0.3\text{ V}$
Operating Temperature Range	
Automotive (Y Version)	−40°C to +125°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
40-lead LFCSP, θ_{JA} Thermal Impedance	30°C/W
Lead Temperature, Soldering (10 sec.)	300°C
IR Reflow, Peak Temperature (< 20 sec.)	235°C

¹ Over voltages at \overline{DBX} , \overline{LDAC} , \overline{CS} , and \overline{W}/R are clamped by internal diodes. Current should be limited to the maximum ratings given.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

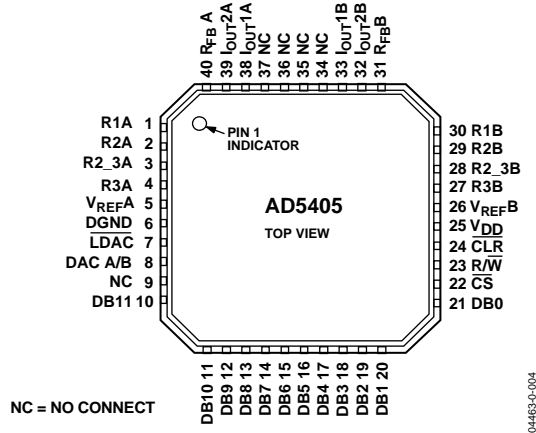


Figure 4. Pin Configuration

Table 4. Pin Function Descriptions

Pin No.	Mnemonic	Function
1 to 4	R1A to R3A	DAC A 4-Quadrant Resistors. Allow a number of configuration modes, including bipolar operation with minimum of external components.
5, 26	V_{REFA} , V_{REFB}	DAC Reference Voltage Input Terminals.
6	DGND	Digital Ground Pin.
7	\overline{LDAC}	Load DAC Input. Allows asynchronous or synchronous updates to the DAC output. The DAC is asynchronously updated when this signal goes low. Alternatively, if this line is held permanently low, an automatic or synchronous update mode is selected whereby the DAC is updated on the rising edge of \overline{CS} .
8	DAC A/B	Selects DAC A or B. Low selects DAC A, while high selects DAC B.
9, 34, 35, 36, 37	NC	Not internally connected.
10 to 21	DB11 to DB0	Parallel Data Bits 11 through 0.
22	\overline{CS}	Chip Select Input. Active low. Used in conjunction with $\overline{R/W}$ to load parallel data to the input latch or to read data from the DAC register. Edge sensitive; when pulled high, the DAC data is latched.
23	$\overline{R/W}$	Read/Write. When low, used in conjunction with \overline{CS} to load parallel data. When high, used in conjunction with \overline{CS} to read back contents of DAC register.
24	\overline{CLR}	Active Low Control Input. Clears DAC output and input and DAC registers.
25	V_{DD}	Positive Power Supply Input. These parts can be operated from a supply of 2.5 V to 5.5 V.
26 to 30	R3B to R1B	DAC B 4-Quadrant Resistors. Allow a number of configuration modes, including bipolar operation with a minimum of external components.
32	I_{OUT2B}	DAC A Analog Ground. This pin typically should be tied to the analog ground of the system, but may be biased to achieve single-supply operation.
33	I_{OUT1B}	DAC B Current Outputs.
38	I_{OUT1A}	DAC A Current Outputs.
39	I_{OUT2A}	DAC A Analog Ground. This pin typically should be tied to the analog ground of the system, but may be biased to achieve single-supply operation.
31, 40	$R_{FB B}$, $R_{FB A}$	External Amplifier Output.

TYPICAL PERFORMANCE CHARACTERISTICS

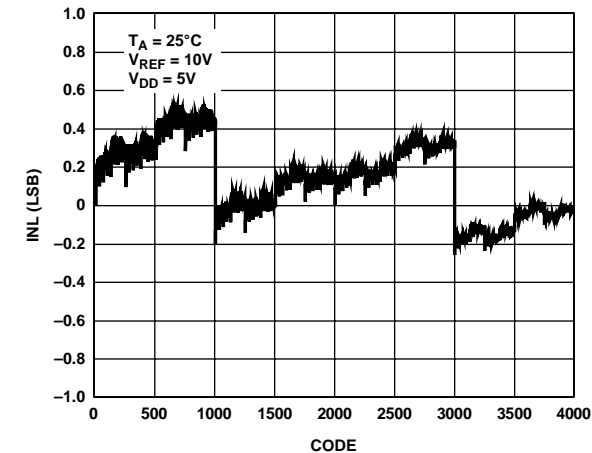


Figure 5. INL vs. Code (12-Bit DAC)

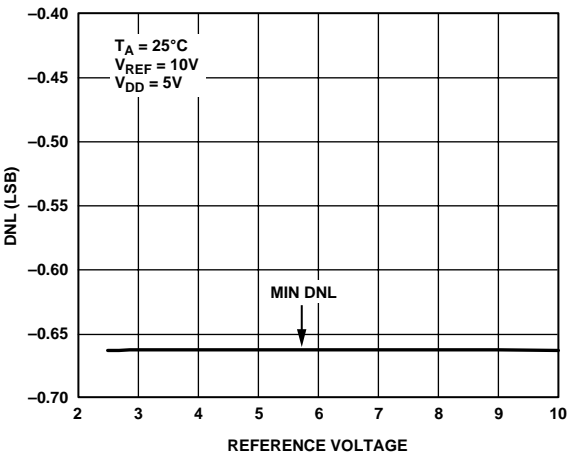


Figure 8. DNL vs. Reference Voltage

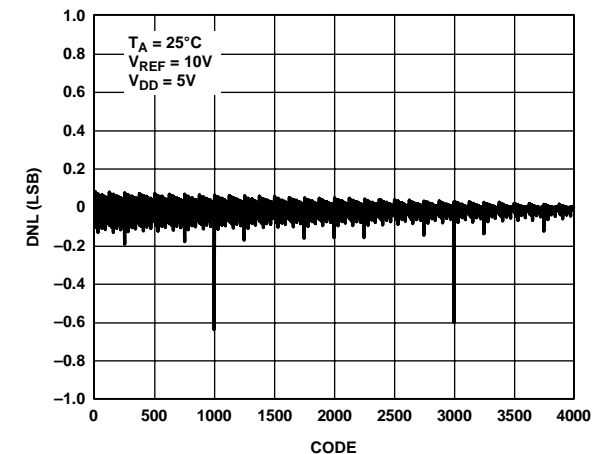


Figure 6. DNL vs. Code (12-Bit DAC)

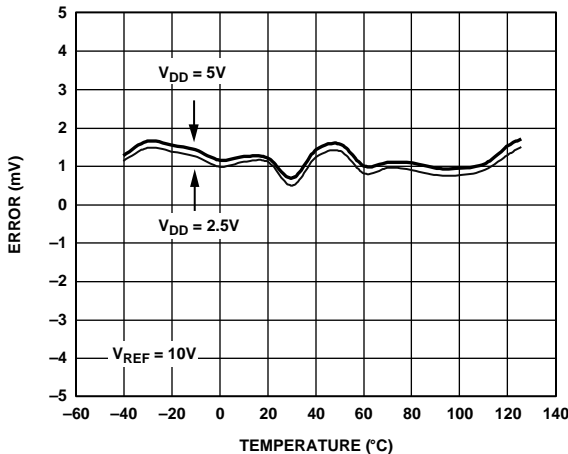


Figure 9. Gain Error vs. Temperature

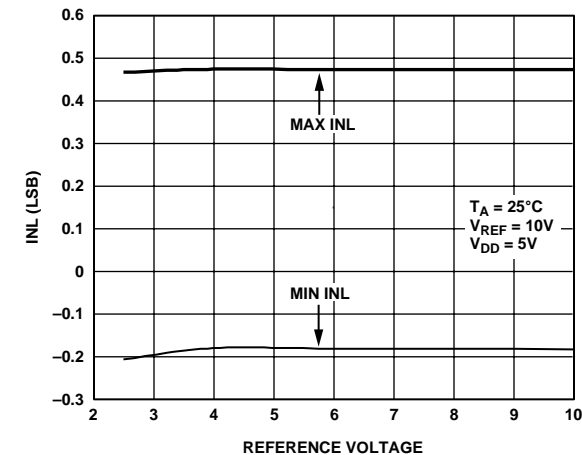


Figure 7. INL vs. Reference Voltage

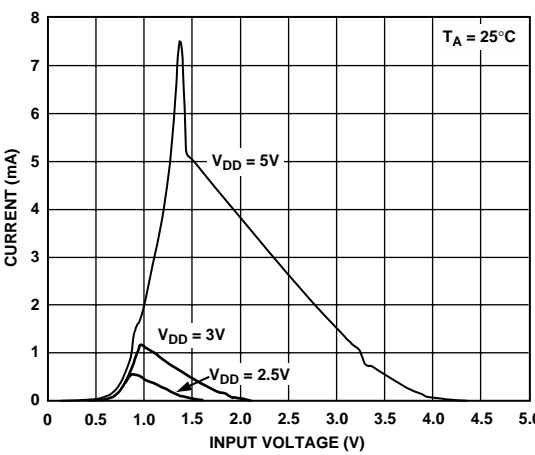


Figure 10. Supply Current vs. Logic Input Voltage

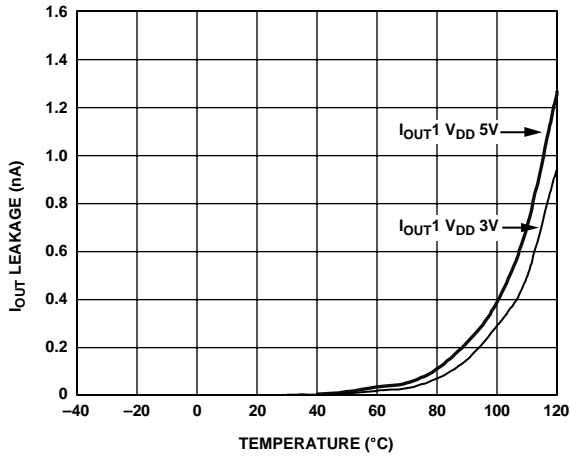


Figure 11. I_{OUT1} Leakage Current vs. Temperature

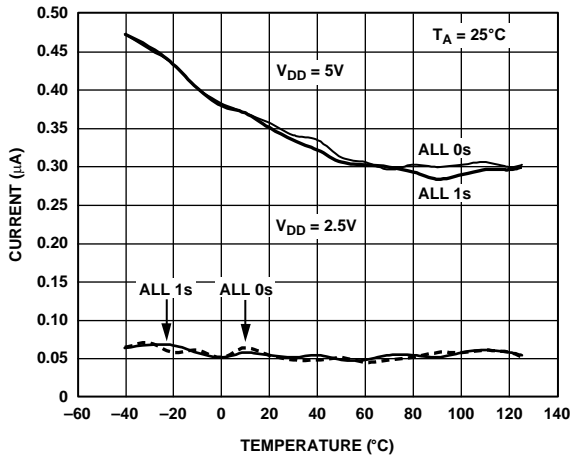


Figure 12. Supply Current vs. Temperature

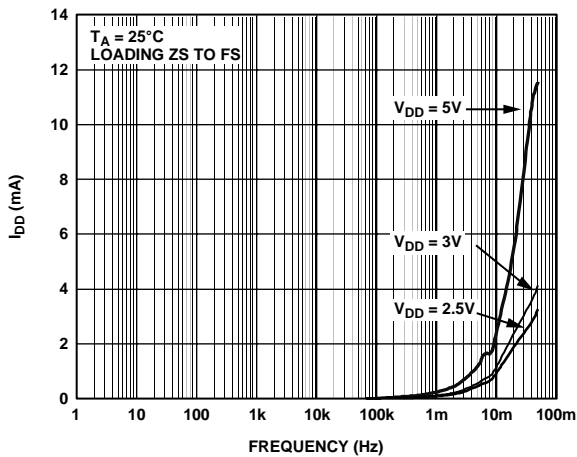


Figure 13. Supply Current vs. Update Rate

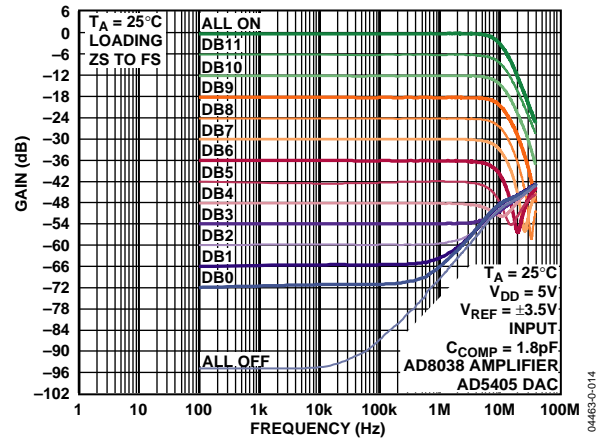


Figure 14. Reference Multiplying Bandwidth vs. Frequency and Code

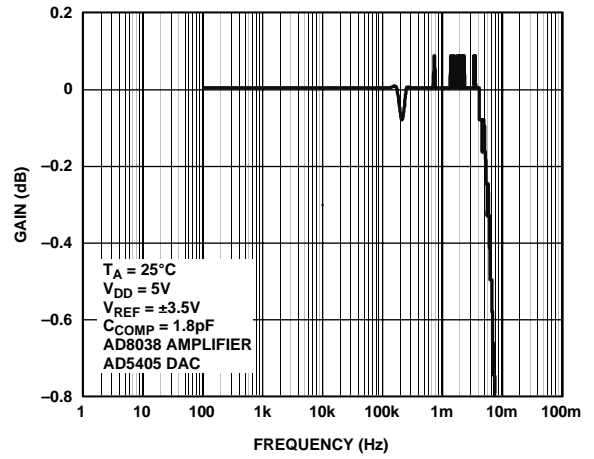


Figure 15. Reference Multiplying Bandwidth—All 1s Loaded

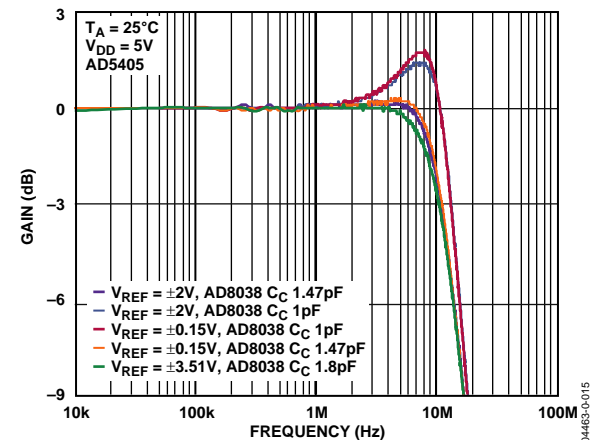


Figure 16. Reference Multiplying Bandwidth vs. Frequency and Compensation Capacitor

AD5405

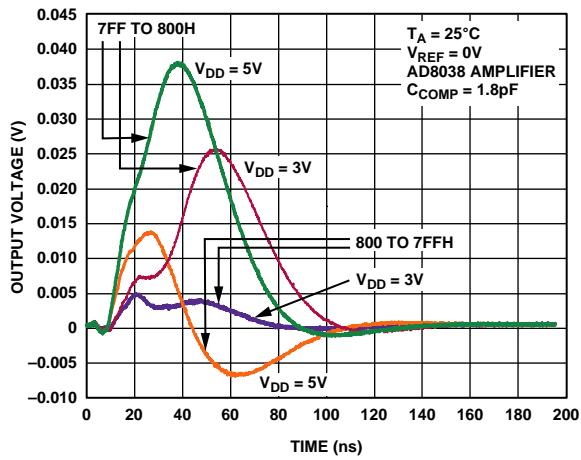


Figure 17. Midscale Transition, $V_{REF} = 0\text{ V}$

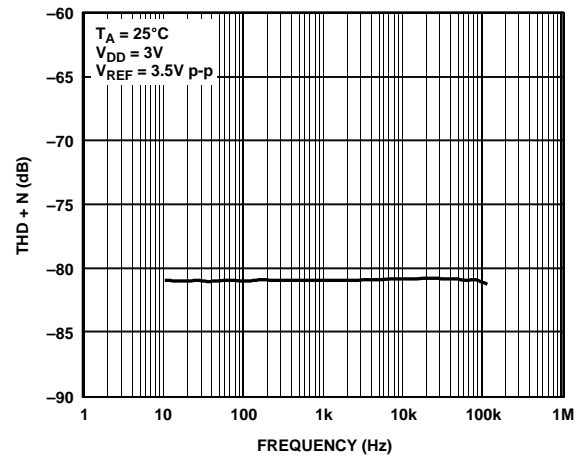


Figure 20. THD and Noise vs. Frequency

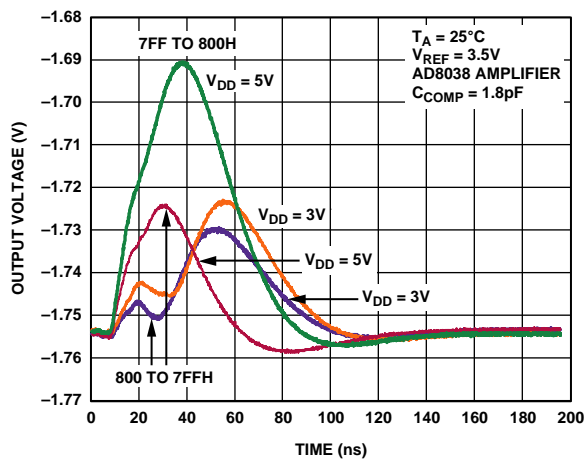


Figure 18. Midscale Transition, $V_{REF} = 3.5\text{ V}$

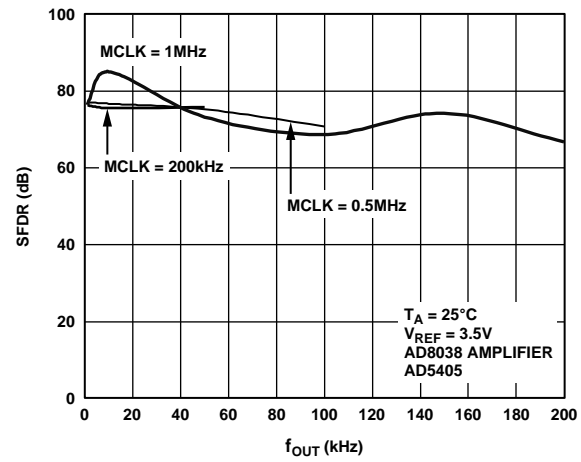


Figure 21. Wideband SFDR vs. f_{OUT} Frequency

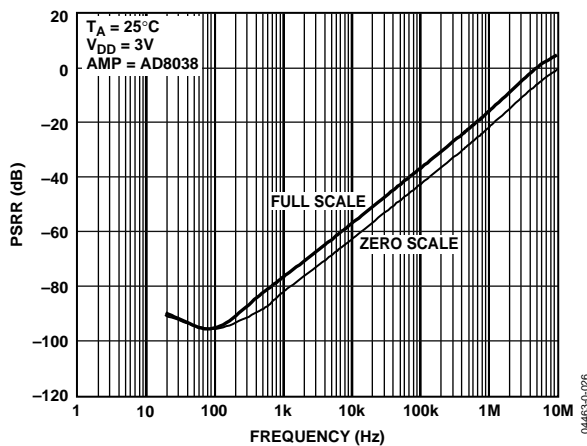


Figure 19. Power Supply Rejection vs. Frequency

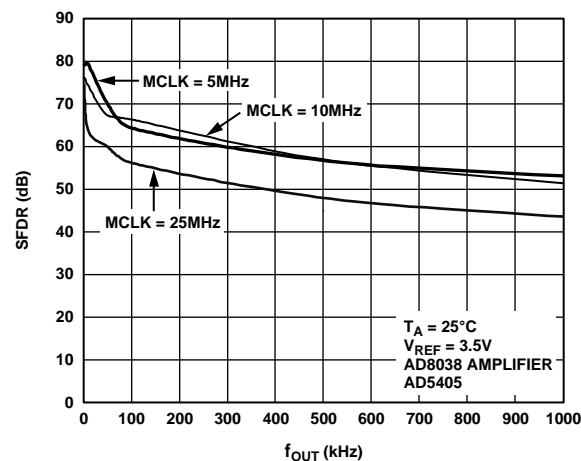


Figure 22. Wideband SFDR vs. f_{OUT} Frequency

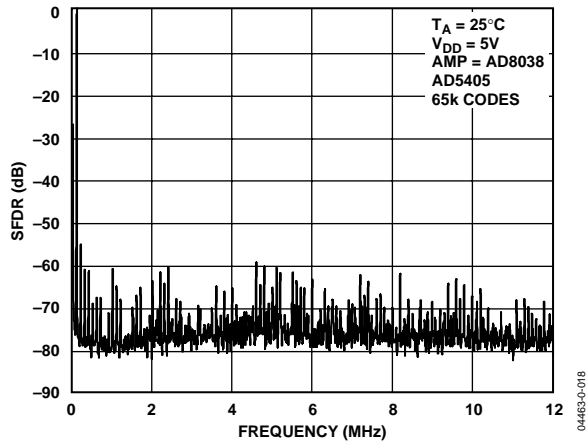


Figure 23. Wideband SFDR, $f_{OUT} = 100\text{ kHz}$, Clock = 25 MHz

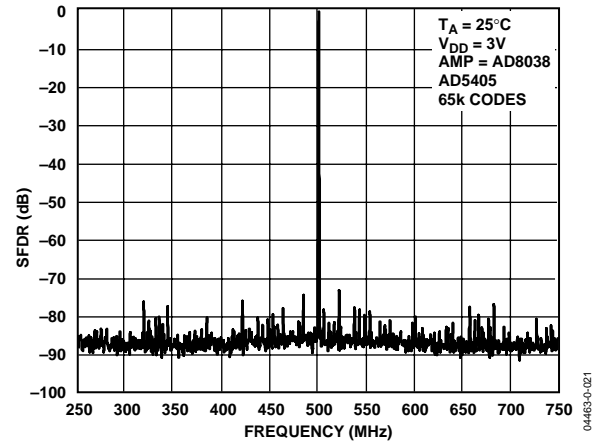


Figure 26. Narrow-Band Spectral Response, $f_{OUT} = 500\text{ kHz}$, Clock = 25 MHz

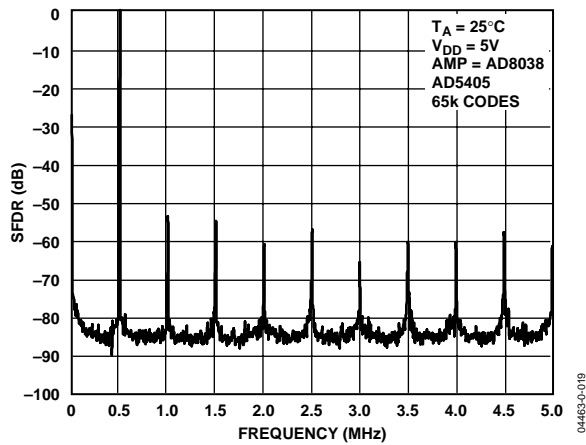


Figure 24. Wideband SFDR, $f_{OUT} = 500\text{ kHz}$, Clock = 10 MHz

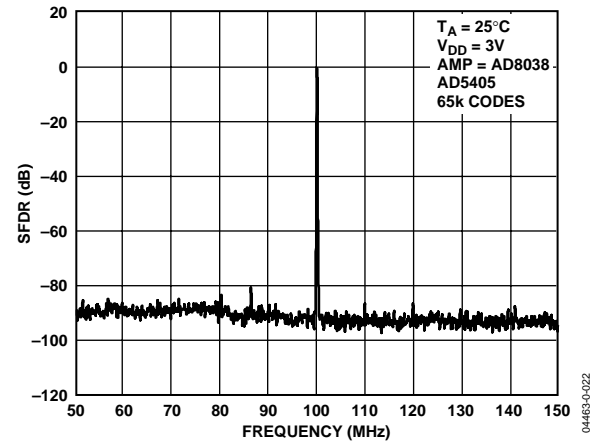


Figure 27. Narrow-Band SFDR, $f_{OUT} = 100\text{ kHz}$, Clock = 25 MHz

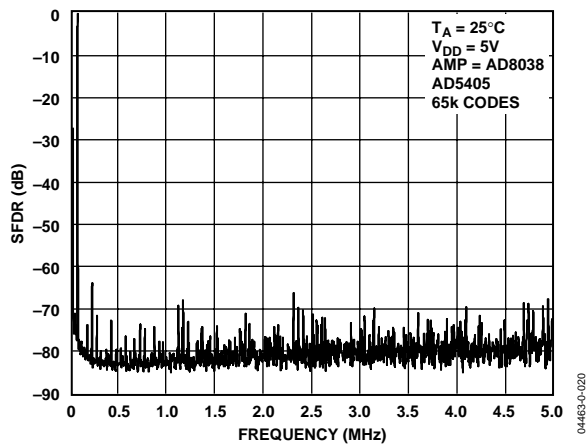


Figure 25. Wideband SFDR, $f_{OUT} = 50\text{ kHz}$, Clock = 10 MHz

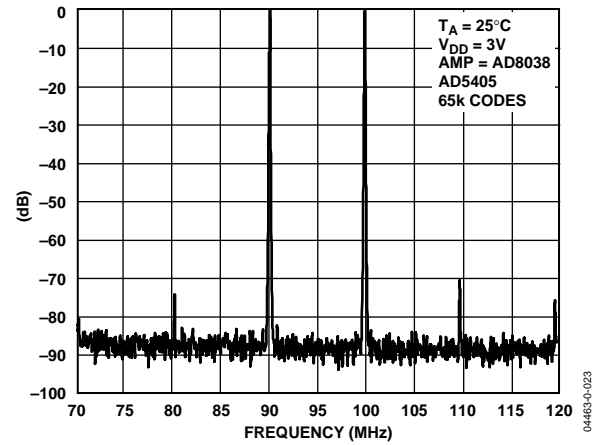


Figure 28. Narrow-Band IMD, $f_{OUT} = 90\text{ kHz}$, 100 kHz, Clock = 10 MHz

AD5405

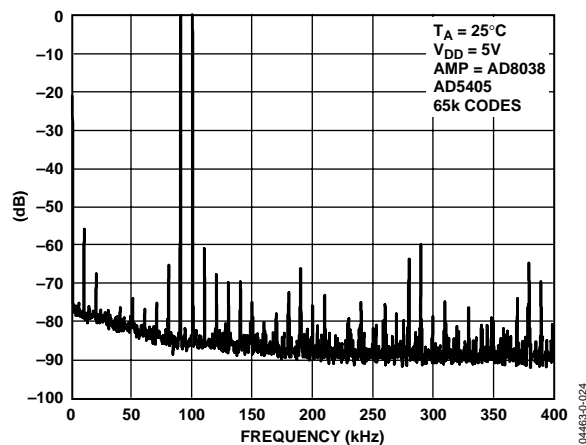


Figure 29. Wideband IMD, $f_{OUT} = 90\text{ kHz}$, 100 kHz , Clock = 25 MHz

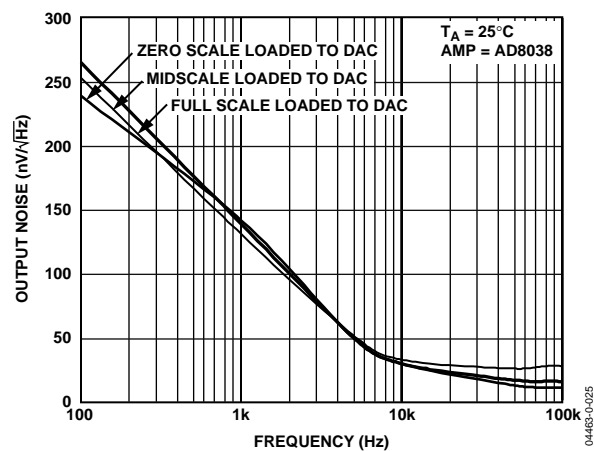


Figure 30. Output Noise Spectral Density

TERMINOLOGY

Relative Accuracy

Relative accuracy or endpoint nonlinearity is a measure of the maximum deviation from a straight line passing through the endpoints of the DAC transfer function. It is measured after adjusting for zero and full scale and is normally expressed in LSBs or as a percentage of full-scale reading.

Differential Nonlinearity

Differential nonlinearity is the difference between the measured change and the ideal 1 LSB change between any two adjacent codes. A specified differential nonlinearity of ± 1 LSB max over the operating temperature range ensures monotonicity.

Gain Error

Gain error or full-scale error is a measure of the output error between an ideal DAC and the actual device output. For this DAC, ideal maximum output is $V_{REF} - 1$ LSB. Gain error of the DACs is adjustable to zero with external resistance.

Output Leakage Current

Output leakage current is current that flows in the DAC ladder switches when these are turned off. For the I_{OUT1} terminal, it can be measured by loading all 0s to the DAC and measuring the I_{OUT1} current. Minimum current flows in the I_{OUT2} line when the DAC is loaded with all 1s.

Output Capacitance

Capacitance from I_{OUT1} or I_{OUT2} to AGND.

Output Current Settling Time

This is the amount of time it takes for the output to settle to a specified level for a full-scale input change. For this device, it is specified with a $100\ \Omega$ resistor to ground.

Digital to Analog Glitch Impulse

The amount of charge injected from the digital inputs to the analog output when the inputs change state. This is typically specified as the area of the glitch in either pA-secs or nV-secs depending upon whether the glitch is measured as a current or voltage signal.

Digital Feedthrough

When the device is not selected, high frequency logic activity on the device's digital inputs is capacitively coupled through the device to show up as noise on the I_{OUT} pins and subsequently into the following circuitry. This noise is digital feedthrough.

Multiplying Feedthrough Error

This is the error due to capacitive feedthrough from the DAC reference input to the DAC I_{OUT1} terminal, when all 0s are loaded to the DAC.

Digital Crosstalk

This is the glitch impulse transferred to the outputs of one DAC in response to a full-scale code change (all 0s to all 1s, and vice versa) in the input register of the other DAC. It is expressed in nV-s.

Analog Crosstalk

This is the glitch impulse transferred to the output of one DAC due to a change in the output of another DAC. It is measured by loading one of the input registers with a full-scale code change (all 0s to all 1s, and vice versa), while keeping LDAC high. Then pulse LDAC low and monitor the output of the DAC whose digital code was not changed. The area of the glitch is expressed in nV-s.

Channel to Channel Isolation

This refers to the proportion of input signal from one DAC's reference input which appears at the output of the other DAC, and is expressed in dBs.

Total Harmonic Distortion (THD)

The DAC is driven by an ac reference. The ratio of the rms sum of the harmonics of the DAC output to the fundamental value is the THD. Usually only the lower-order harmonics are included, such as the second to the fifth.

$$THD = 20 \log \sqrt{\frac{V_2^2 + V_3^2 + V_4^2 + V_5^2}{V_1^2}}$$

Intermodulation Distortion

The DAC is driven by two combined sine wave references of frequencies f_a and f_b . Distortion products are produced at sum and difference frequencies of $m f_a \pm n f_b$ where $m, n = 0, 1, 2, 3, \dots$. Intermodulation terms are those for which m or n is not equal to zero. The second-order terms include $(f_a + f_b)$ and $(f_a - f_b)$ and the third-order terms are $(2f_a + f_b)$, $(2f_a - f_b)$, $(f + 2f_a + 2f_b)$ and $(f_a - 2f_b)$. IMD is defined as

$$IMD = 20 \log \frac{(\text{rms sum of the sum and diff distortion products})}{\text{rms amplitude of the fundamental}}$$

Compliance Voltage Range

The maximum range of (output) terminal voltage for which the device provides the specified characteristics.

AD5405

GENERAL DESCRIPTION

DAC SECTION

The AD5405 is a 12-bit, dual-channel, current-output DAC consisting of a standard inverting R-2R ladder configuration. Figure 31 shows a simplified diagram for a single channel of the AD5405. The feedback resistor R_{FB} has a value of $2R$. The value of R is typically $10\text{ k}\Omega$ (minimum $8\text{ k}\Omega$ and maximum $12\text{ k}\Omega$). If I_{OUT1A} and I_{OUT2A} are kept at the same potential, a constant current flows in each ladder leg, regardless of digital input code. Thus, the input resistance presented at V_{REF} is always constant.

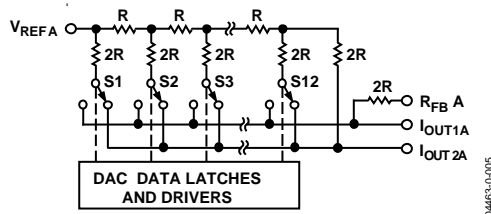


Figure 31. Simplified Ladder Configuration

Access is provided to the V_{REF} , R_{FB} , I_{OUT1} , and I_{OUT2} terminals of each DAC, making the device extremely versatile and allowing it to be configured in several different operating modes, such as for unipolar output, bipolar output, or single-supply mode.

CIRCUIT OPERATION

Unipolar Mode

Using a single op amp, this DAC can easily be configured to provide 2-quadrant multiplying operation or a unipolar output voltage swing, as shown in Figure 32.

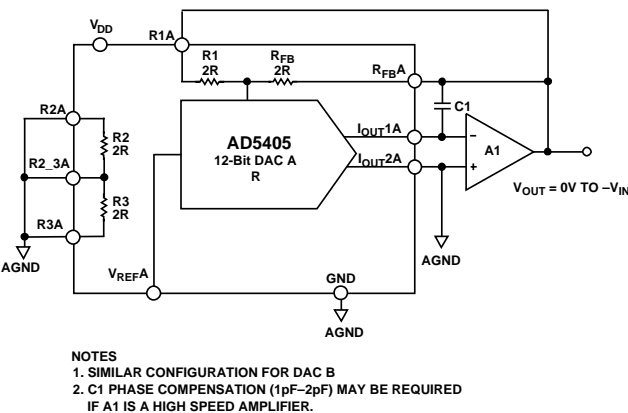


Figure 32. Unipolar Operation

When an output amplifier is connected in unipolar mode, the output voltage is given by

$$V_{OUT} = -D/2^n \times V_{REF}$$

where D is the fractional representation of the digital word loaded to the DAC, and n is the resolution of the DAC.

$$D = 0 \text{ to } 4095$$

With a fixed 10 V reference, the circuit shown in Figure 32 gives a unipolar 0 V to -10 V output voltage swing. When V_{IN} is an ac signal, the circuit performs 2-quadrant multiplication.

Table 5 shows the relationship between digital code and expected output voltage for unipolar operation.

Table 5. Unipolar Code Table

Digital Input	Analog Output (V)
1111 1111	$-V_{REF}$ (4095/4096)
1000 0000	$-V_{REF}$ (2048/4096) = $-V_{REF}/2$
0000 0001	$-V_{REF}$ (1/4096)
0000 0000	$-V_{REF}$ (0/4096) = 0

Bipolar Operation

In some applications, it may be necessary to generate full 4-quadrant multiplying operation or a bipolar output swing. This can be easily accomplished by using another external amplifier, as shown in Figure 33.

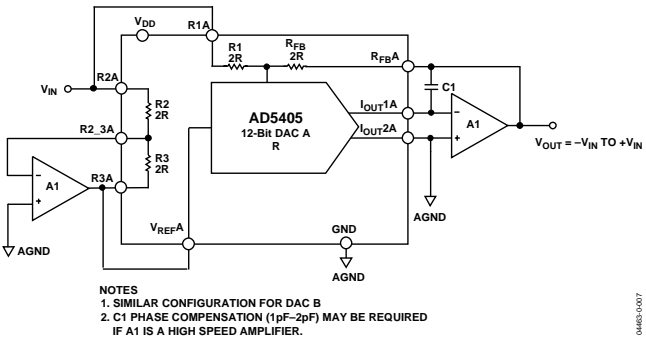


Figure 33. Bipolar Operation (4-Quadrant Multiplication)

When in bipolar mode, the output voltage is given by

$$V_{OUT} = V_{REF} \times D/2^{n-1} \times V_{REF}$$

where D is the fractional representation of the digital word loaded to the DAC, in the range of 0 to 4095, and n is the number of bits. When V_{IN} is an ac signal, the circuit performs 4-quadrant multiplication.

Table 6 shows the relationship between the digital code and the expected output voltage for bipolar operation.

Table 6. Bipolar Code Table

Digital Input	Analog Output (V)
1111 1111	$+V_{REF}$ (2047/2048)
1000 0000	0
0000 0001	$-V_{REF}$ (2047/2048)
0000 0000	$-V_{REF}$ (2048/2048)

Stability

In the I-to-V configuration, the I_{OUT} of the DAC and the inverting node of the op amp must be connected as close as possible, and proper PCB layout techniques must be employed. Because every code change corresponds to a step function, gain peaking may occur if the op amp has limited GBP and there is excessive parasitic capacitance at the inverting node. This parasitic capacitance introduces a pole into the open loop response which can cause ringing or instability in the closed-loop applications circuit.

An optional compensation capacitor, C_1 , can be added in parallel with R_{FB} for stability, as shown in Figure 32 and Figure 33. Too small a value of C_1 can produce ringing at the output, while too large a value can adversely affect the settling time. C_1 should be found empirically, but 1 pF to 2 pF is generally adequate for the compensation.

SINGLE-SUPPLY APPLICATIONS

Voltage Switching Mode of Operation

Figure 34 shows these DACs operating in the voltage switching mode. The reference voltage, V_{IN} , is applied to the I_{OUT1} pin, I_{OUT2} is connected to AGND, and the output voltage is available at the V_{REF} terminal. In this configuration, a positive reference voltage results in a positive output voltage, making single-supply operation possible. The output from the DAC is voltage at a constant impedance (the DAC ladder resistance). Thus an op amp is necessary to buffer the output voltage. The reference input no longer sees a constant input impedance, but one that varies with code. So, the voltage input should be driven from a low impedance source.

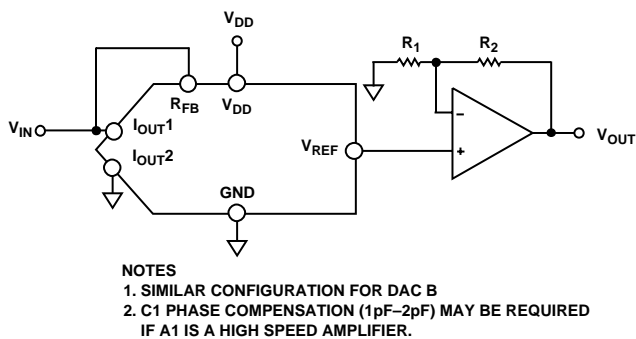


Figure 34. Single-Supply Voltage Switching Mode

Note that V_{IN} is limited to low voltages because the switches in the DAC ladder no longer have the same source-drain drive voltage. As a result, their on resistance differs and degrades the integral linearity of the DAC. Also, V_{IN} must not go negative by more than 0.3 V or an internal diode turns on, exceeding the max ratings of the device. In this type of application, the full range of multiplying capability of the DAC is lost.

POSITIVE OUTPUT VOLTAGE

Note that the output voltage polarity is opposite to the V_{REF} polarity for dc reference voltages. In order to achieve a positive voltage output, an applied negative reference to the input of the DAC is preferred over the output inversion through an inverting amplifier because of the resistor's tolerance errors. To generate a negative reference, the reference can be level shifted by an op amp such that the V_{OUT} and GND pins of the reference become the virtual ground and -2.5 V respectively, as shown in Figure 35.

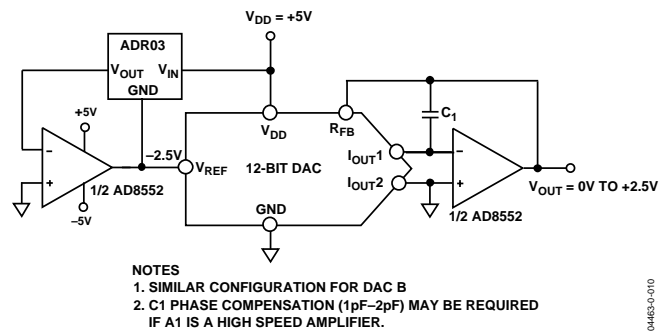


Figure 35. Positive Voltage Output with Minimum Components

ADDING GAIN

In applications where the output voltage is required to be greater than V_{IN} , gain can be added with an additional external amplifier or it can also be achieved in a single stage. Consider the effect of temperature coefficients of the thin film resistors of the DAC. Simply placing a resistor in series with the R_{FB} resistor causes mismatches in the temperature coefficients resulting in larger gain temperature coefficient errors. Instead, the circuit of Figure 36 is a recommended method of increasing the gain of the circuit. R_1 , R_2 , and R_3 should all have similar temperature coefficients, but they need not match the temperature coefficients of the DAC. This approach is recommended in circuits where gains of > 1 are required.

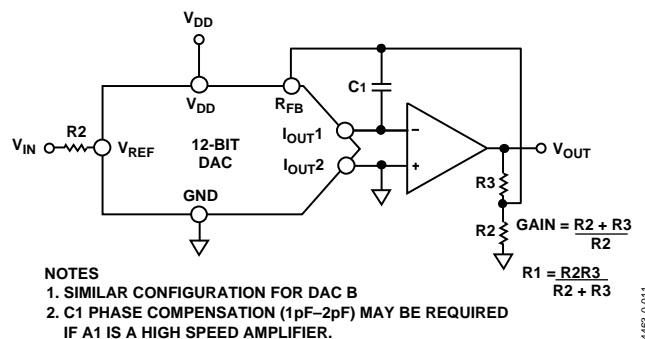


Figure 36. Increasing Gain of Current Output DAC

Table 7. Suitable ADI Precision References Recommended for Use with AD5405 DACs

Reference	Output Voltage	Initial Tolerance	Temperature Drift	0.1 Hz to 10 Hz noise	Package
ADR01	10 V	0.1%	3 ppm/°C	20 μ V p-p	SC70, TSOT, SOIC
ADR02	5 V	0.1%	3 ppm/°C	10 μ V p-p	SC70, TSOT, SOIC
ADR03	2.5 V	0.2%	3 ppm/°C	10 μ V p-p	SC70, TSOT, SOIC
ADR425	5 V	0.04%	3 ppm/°C	3.4 μ V p-p	MSOP, SOIC

Table 8. Precision ADI Op Amps Suitable for Use with AD5405 DACs

Part No.	Max Supply Voltage V	V _{OS} (max) μ V	I _B (max) nA	GBP MHz	Slew Rate V/ μ s
OP97	\pm 20	25	0.1	0.9	0.2
OP1177	\pm 18	60	2	1.3	0.7
AD8551	+6	5	0.05	1.5	0.4

Table 9. High Speed ADI Op Amps Suitable for Use with AD5405 DACs

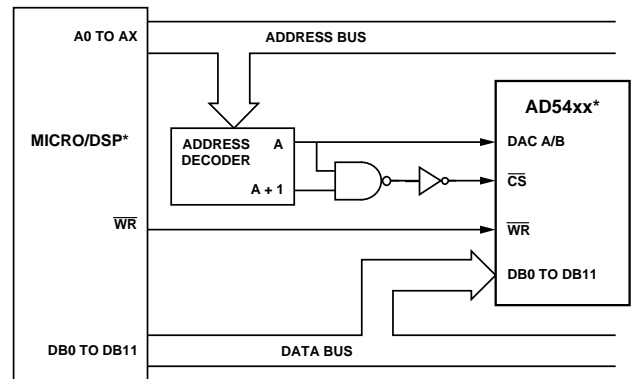
Part No.	Max Supply Voltage V	V _{OS} (max) μ V	I _B (max) nA	BW @ A _{CL} MHz	Slew Rate V/ μ s
AD8065	\pm 12	1500	0.01	145	180
AD8021	\pm 12	1000	1000	200	100
AD8038	\pm 5	3000	0.75	350	425

PARALLEL INTERFACE

Data is loaded to the AD5405 in the format of a 12-bit parallel word. Control lines $\overline{\text{CS}}$ and $\text{R}/\overline{\text{W}}$ allow data to be written to or read from the DAC register. A write event takes place when $\overline{\text{CS}}$ and $\text{R}/\overline{\text{W}}$ are brought low, data available on the data lines fills the shift register, and the rising edge of $\overline{\text{CS}}$ latches the data and transfers the latched data word to the DAC register. The DAC latches are not transparent, thus a write sequence must consist of a falling and rising edge on $\overline{\text{CS}}$ to ensure data is loaded to the DAC register and its analog equivalent reflected on the DAC $\overline{\text{CS}}$ output. A read event takes place when $\text{R}/\overline{\text{W}}$ is held high and $\overline{\text{CS}}$ is brought low. Data is loaded from the DAC register back to the input register and out onto the data line where it can be read back to the controller for verification or diagnostic purposes. The input and DAC registers of these devices are not transparent, so a falling and rising edge of $\overline{\text{CS}}$ is required to load each data-word.

MICROPROCESSOR INTERFACING

The AD5405 can be interfaced to a variety of 16-bit microcontrollers or DSP processors. Figure 38 shows the AD5405 DAC interfaced to a generic 16-bit microcontroller/DSP processor. Microprocessor interfacing to this family of DAC is via a data bus that uses a standard protocol compatible with microcontrollers and DSP processors. The address decoder selects DAC A or DAC B and also to loads parallel data to the input latch or to read data from the DAC using an AND gate.



*ADDITIONAL PINS OMITTED FOR CLARITY

Figure 38. AD54xx to Parallel Interface

PCB LAYOUT AND POWER SUPPLY DECOUPLING

In any circuit where accuracy is important, careful consideration of the power supply and ground return layout helps to ensure the rated performance. The printed circuit board on which the AD5405 is mounted should be designed so that the analog and digital sections are separated, and confined to certain areas of the board. If the DAC is in a system where multiple devices require an AGND-to-DGND connection, the connection should be made at one point only. The star ground point should be established as close as possible to the device.

AD5405

These DACs should have ample supply bypassing of 10 μF in parallel with 0.1 μF on the supply located as close to the package as possible, ideally right up against the device. The 0.1 μF capacitor should have low effective series resistance (ESR) and effective series inductance (ESI), like the common ceramic types that provide a low impedance path to ground at high frequencies, to handle transient currents due to internal logic switching. Low ESR 1 μF to 10 μF tantalum or electrolytic capacitors should also be applied at the supplies to minimize transient disturbance and filter out low frequency ripple.

Fast switching signals such as clocks should be shielded with digital ground to avoid radiating noise to other parts of the board, and should never be run near the reference inputs.

Avoid crossover of digital and analog signals. Traces on opposite sides of the board should run at right angles to each other. This reduces the effects of feedthrough on the board. A microstrip technique is by far the best, but not always possible with a double-sided board. In this technique, the component side of the board is dedicated to the ground plane while signal traces are placed on the soldered side.

It is good practice to employ compact, minimum lead length PCB layout design. Leads to the input should be as short as possible to minimize IR drops and stray inductance.

The PCB metal traces between V_{REF} and R_{FB} should also be matched to minimize gain error. To maximize high frequency performance, the I-to-V amplifier should be located as close to the device as possible.

EVALUATION BOARD FOR THE DACS

The evaluation board consists of a DAC and a current-to-voltage amplifier, the AD8065. Included on the evaluation board is a 10 V reference, the ADR01. An external reference may also be applied via an SMB input.

The evaluation kit consists of a CD-ROM with self-installing PC software to control the DAC. The software simply allows the user to write a code to the device.

POWER SUPPLIES FOR THE EVALUATION BOARD

The board requires $\pm 12\text{ V}$ and 5 V supplies. The 12 V V_{DD} and V_{SS} are used to power the output amplifier, while the 5 V is used to power the DAC (V_{DD1}) and transceivers (V_{CC}).

Both supplies are decoupled to their respective ground plane with 10 μF tantalum and 0.1 μF ceramic capacitors.

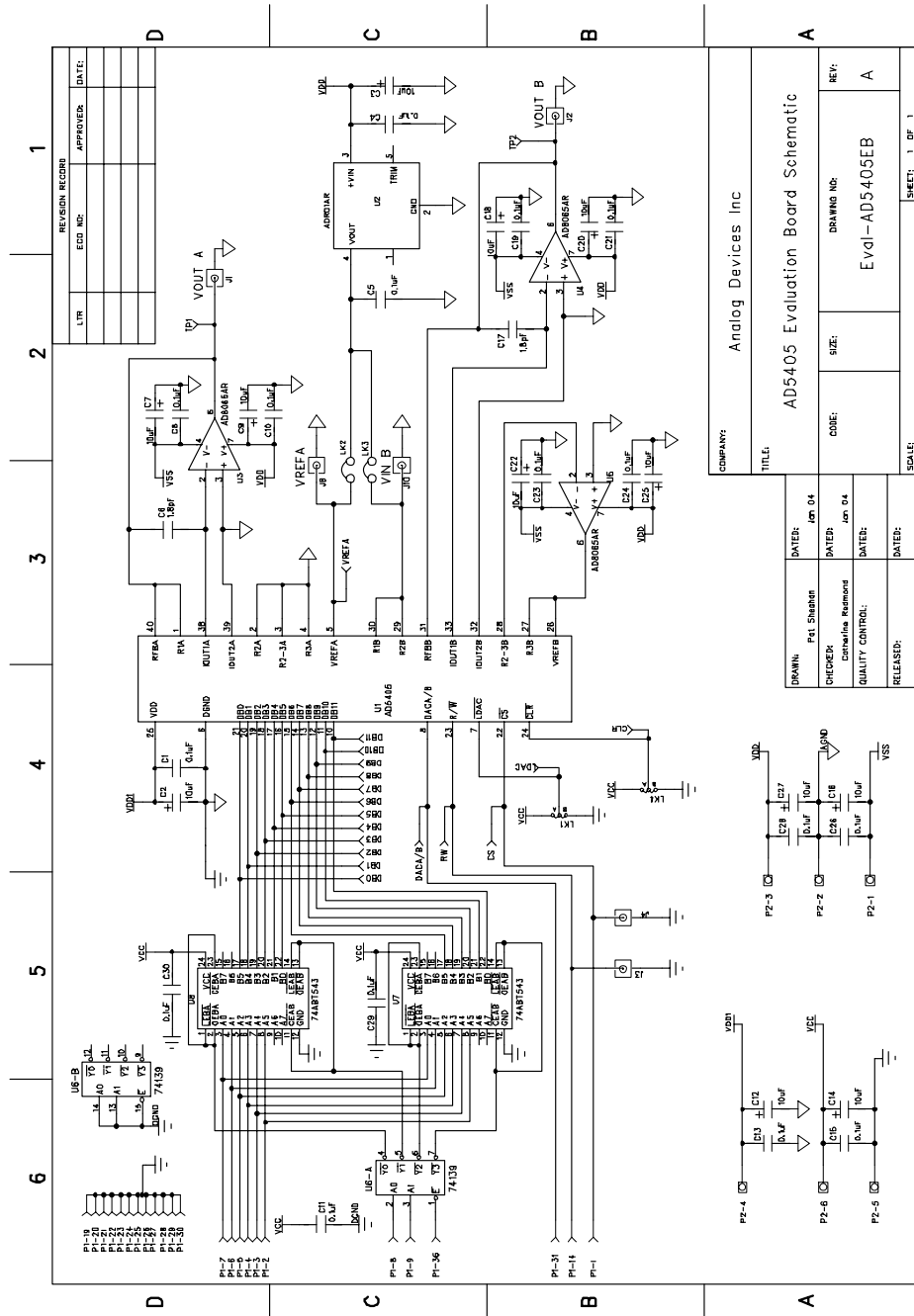


Figure 39. Schematic of AD5405 Evaluation Board

04463-0-045

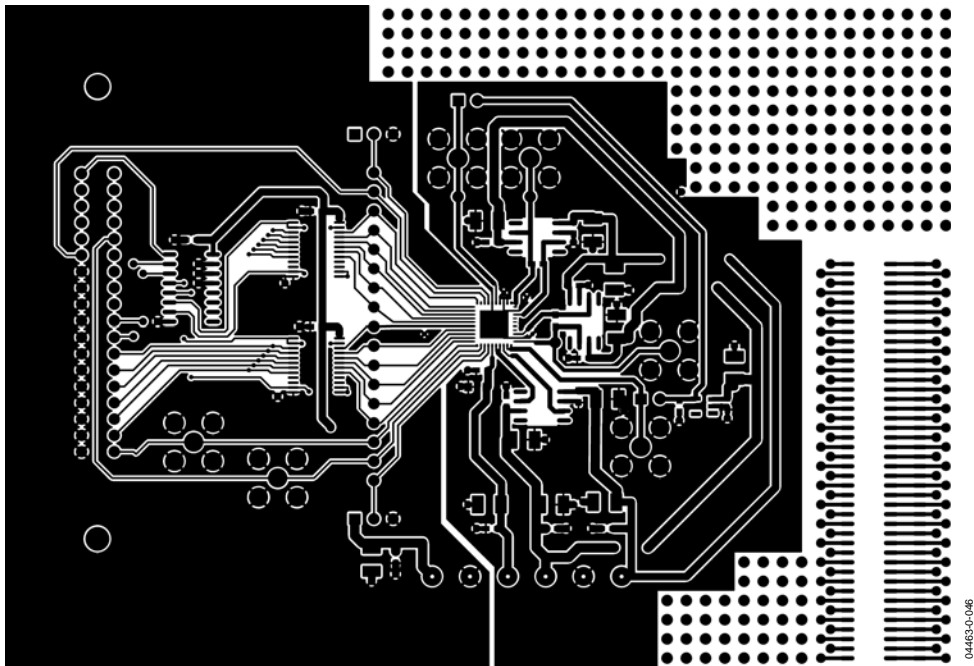


Figure 40. Component-Side Artwork

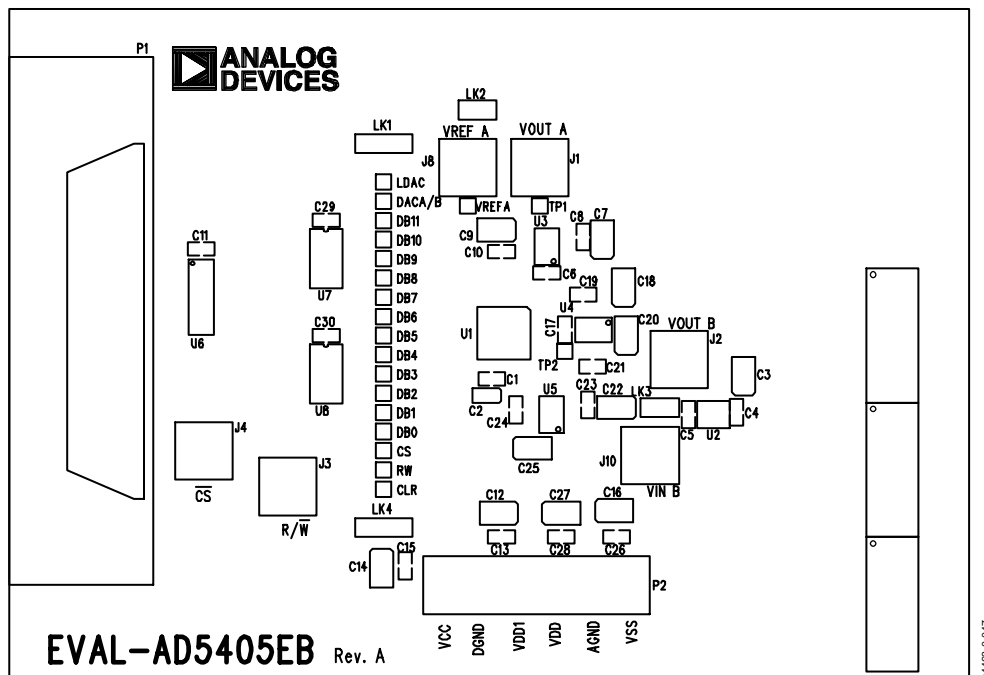


Figure 41. Silkscreen—Component-Side View (Top Layer)

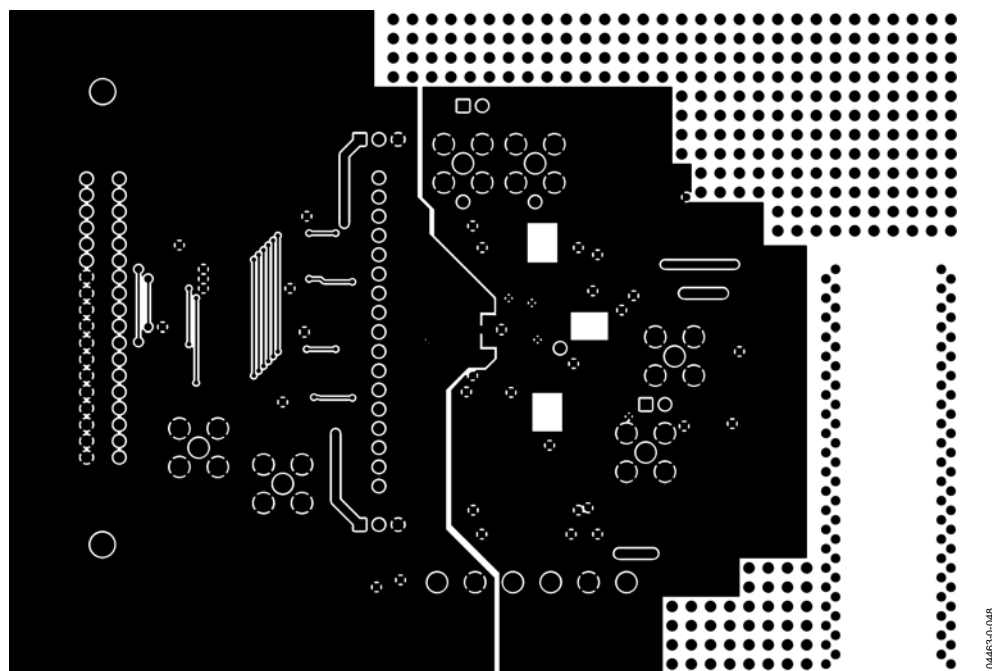


Figure 42. Solder-Side Artwork

AD5405

OVERVIEW OF AD54xx DEVICES

Table 10.

Part No.	Resolution	No. DACs	INL(LSB)	Interface	Package	Features
AD5424	8	1	± 0.25	Parallel	RU-16, CP-20	10 MHz BW, 17 ns \overline{CS} Pulse Width
AD5426	8	1	± 0.25	Serial	RM-10	10 MHz BW, 50 MHz Serial
AD5428	8	2	± 0.25	Parallel	RU-20	10 MHz BW, 17 ns \overline{CS} Pulse Width
AD5429	8	2	± 0.25	Serial	RU-10	10 MHz BW, 50 MHz Serial
AD5450	8	1	± 0.25	Serial	RJ-8	10 MHz BW, 50 MHz Serial
AD5432	10	1	± 0.5	Serial	RM-10	10 MHz BW, 50 MHz Serial
AD5433	10	1	± 0.5	Parallel	RU-20, CP-20	10 MHz BW, 17 ns \overline{CS} Pulse Width
AD5439	10	2	± 0.5	Serial	RU-16	10 MHz BW, 50 MHz Serial
AD5440	10	2	± 0.5	Parallel	RU-24	10 MHz BW, 17 ns \overline{CS} Pulse Width
AD5451	10	1	± 0.25	Serial	RJ-8	10 MHz BW, 50 MHz Serial
AD5443	12	1	± 1	Serial	RM-10	10 MHz BW, 50 MHz Serial
AD5444	12	1	± 0.5	Serial	RM-8	10 MHz BW, 50 MHz Serial
AD5415	12	2	± 1	Serial	RU-24	10 MHz BW, 58 MHz Serial
AD5445	12	2	± 1	Parallel	RU-20, CP-20	10 MHz BW, 17 ns \overline{CS} Pulse Width
AD5447	12	2	± 1	Parallel	RU-24	10 MHz BW, 17 ns \overline{CS} Pulse Width
AD5449	12	2	± 1	Serial	RU-16	10 MHz BW, 50 MHz Serial
AD5452	12	1	± 0.5	Serial	RJ-8, RM-8	10 MHz BW, 50 MHz Serial
AD5446	14	1	± 1	Serial	RM-8	10 MHz BW, 50 MHz Serial
AD5453	14	1	± 2	Serial	UJ-8, RM-8	10 MHz BW, 50 MHz Serial
AD5553	14	1	± 1	Serial	RM-8	4 MHz BW, 50 MHz Serial Clock
AD5556	14	1	± 1	Parallel	RU-28	4 MHz BW, 20 ns \overline{WR} Pulse Width
AD5555	14	2	± 1	Serial	RM-8	4 MHz BW, 50 MHz Serial Clock
AD5557	14	2	± 1	Parallel	RU-38	4 MHz BW, 20 ns \overline{WR} Pulse Width
AD5543	16	1	± 2	Serial	RM-8	4 MHz BW, 50 MHz Serial Clock
AD5546	16	1	± 2	Parallel	RU-28	4 MHz BW, 20 ns \overline{WR} Pulse Width
AD5545	16	2	± 2	Serial	RU-16	4 MHz BW, 50 MHz Serial Clock
AD5547	16	2	± 2	Parallel	RU-38	4 MHz BW, 20 ns \overline{WR} Pulse Width

OUTLINE DIMENSIONS

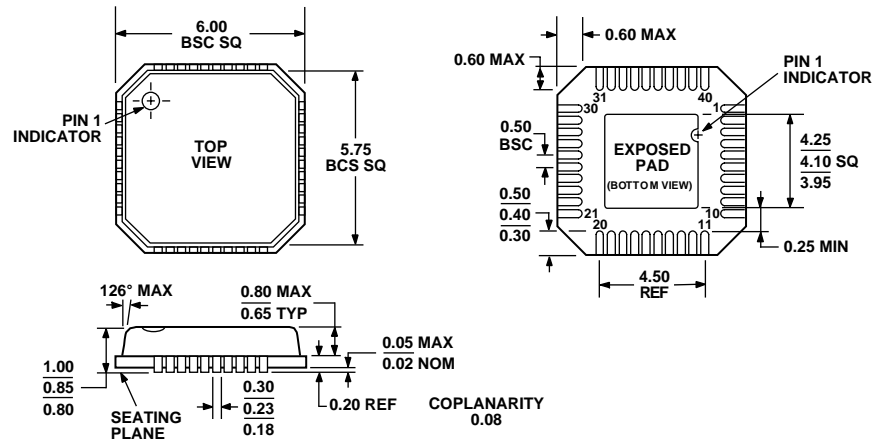


Figure 43. 40 Lead LFCSP
(CP-40)

Dimensions shown in inches and (mm)

ORDERING GUIDE

Model	Resolution	INL (LSBs)	Temperature Range	Package Description	Package Option
AD5405YCP	12	±1	−40°C to +125°C	LFCSP	CP-40
AD5405YCP-REEL	12	±1	−40°C to +125°C	LFCSP	CP-40
AD5405YCP-REEL7	12	±1	−40°C to +125°C	LFCSP	CP-40
EVAL-AD5405EB				Evaluation Kit	

AD5405

NOTES